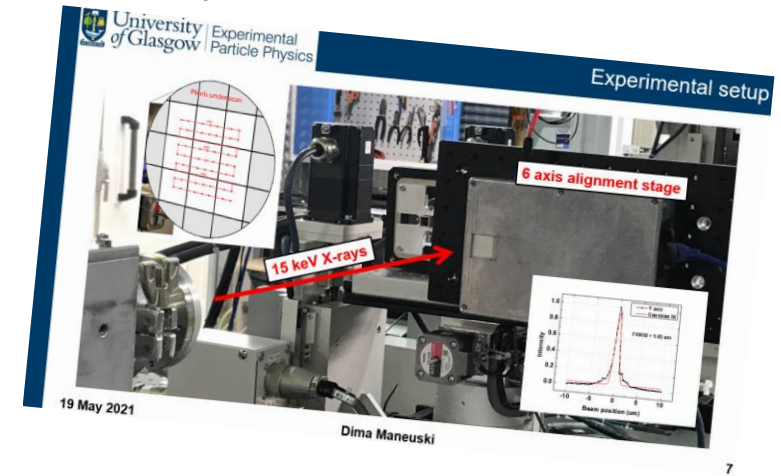
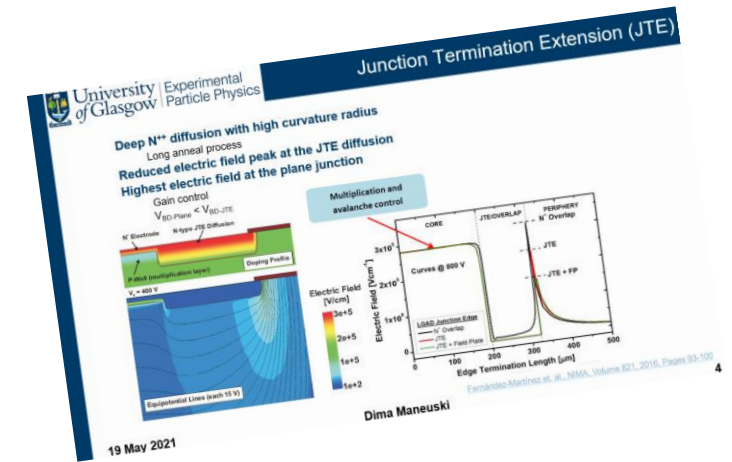


Performance studies of Low Gain Avalanche Detectors coupled to the Timepix3 ASIC

Dima Maneuski, University of Glasgow
Jerome Alozy, CERN
Richard Bates, University of Glasgow
Mark Bullough, Micron Semiconductor Ltd
Lars Eklund, University of Uppsala
Lojius Lombigit, University of Glasgow
Neil Moffat, CNM Barcelona
Nicola Tartoni, Diamond Light Source
Mark Williams, University of Edinburgh

Table of contents

- Low Gain Avalanche Diodes (LGADs)
 - Research agenda and motivation
- Experiments at Diamond Light Source
 - Experimental setup
 - Devices under test
 - Results and discussion
- Future work
- Conclusions



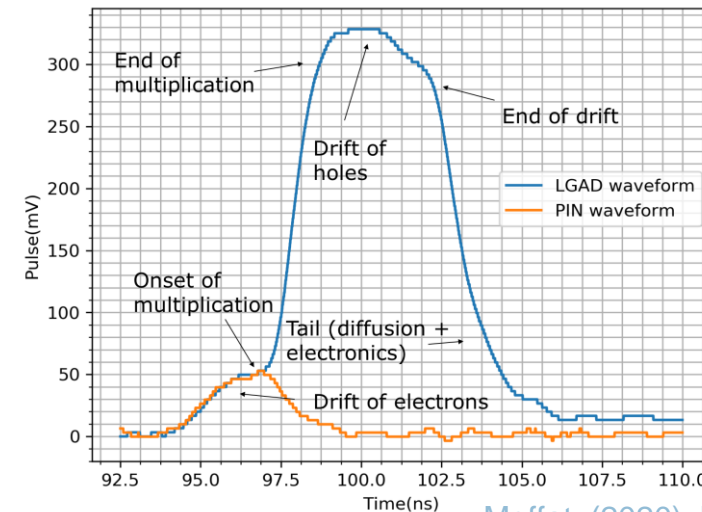
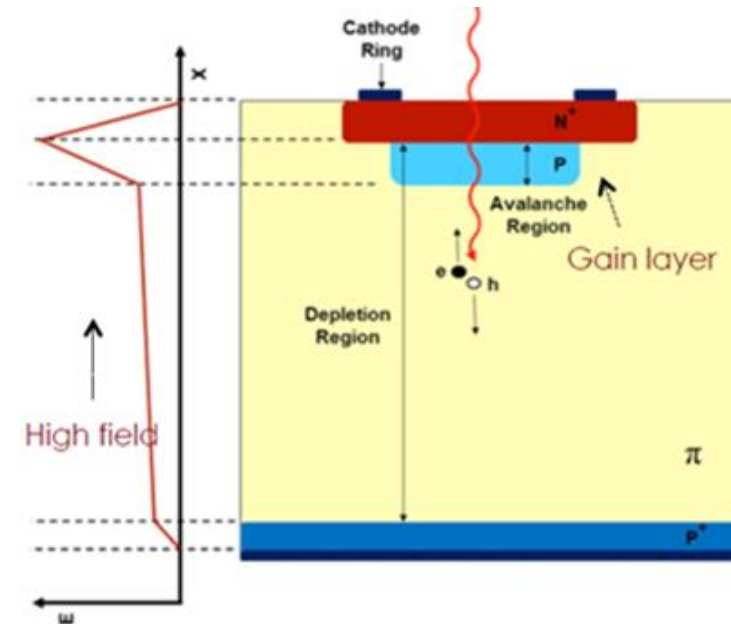
Research agenda and motivation

- Fast timing silicon pixel detectors (sub 100 ps)
- “Tender” energy x-rays detectors (and below)

- Understand LGAD technology
- Create simulation models
- Develop fabrication process
- Build characterisation infrastructure
- Explore potential applications

- Synchrotron applications
- LHCb VELO upgrade

LGAD principle



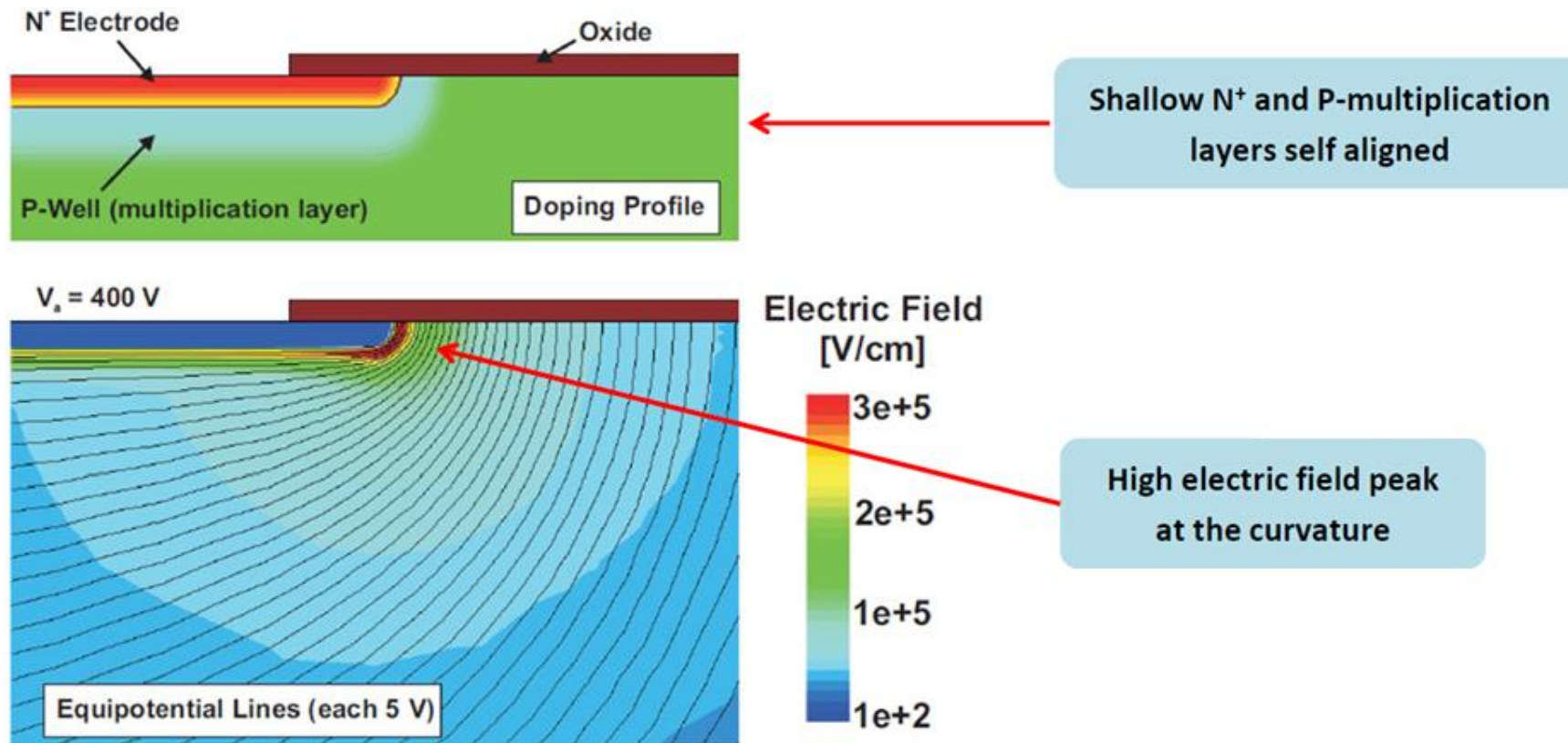
[Moffat, \(2020\), PhD thesis](#)

The electric field at the corner curved section of the N^+/P^+ junction is much higher than that of the flat junction region

where Gain is required

Avalanche at the N^+/P^+ curvature at a very low reverse voltage

-> premature breakdown



Deep N⁺⁺ diffusion with high curvature radius

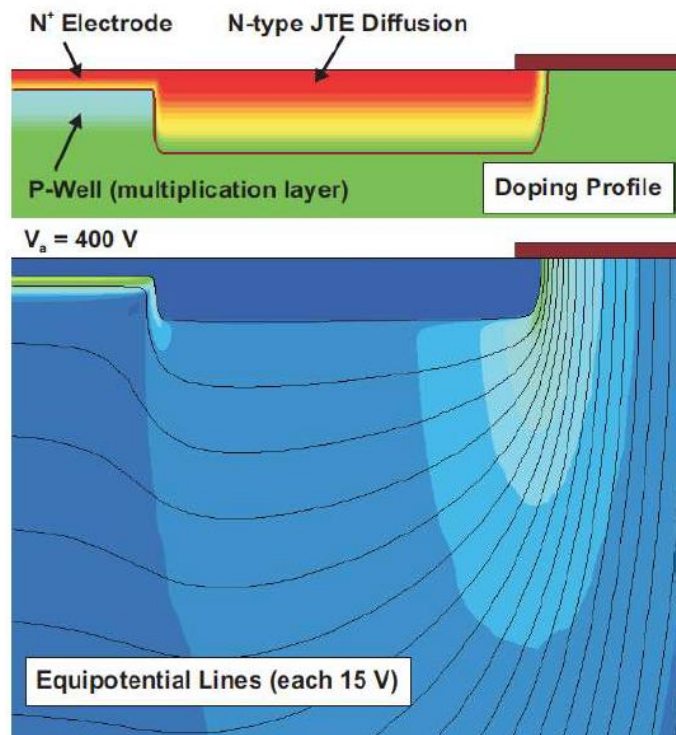
Long anneal process

Reduced electric field peak at the JTE diffusion

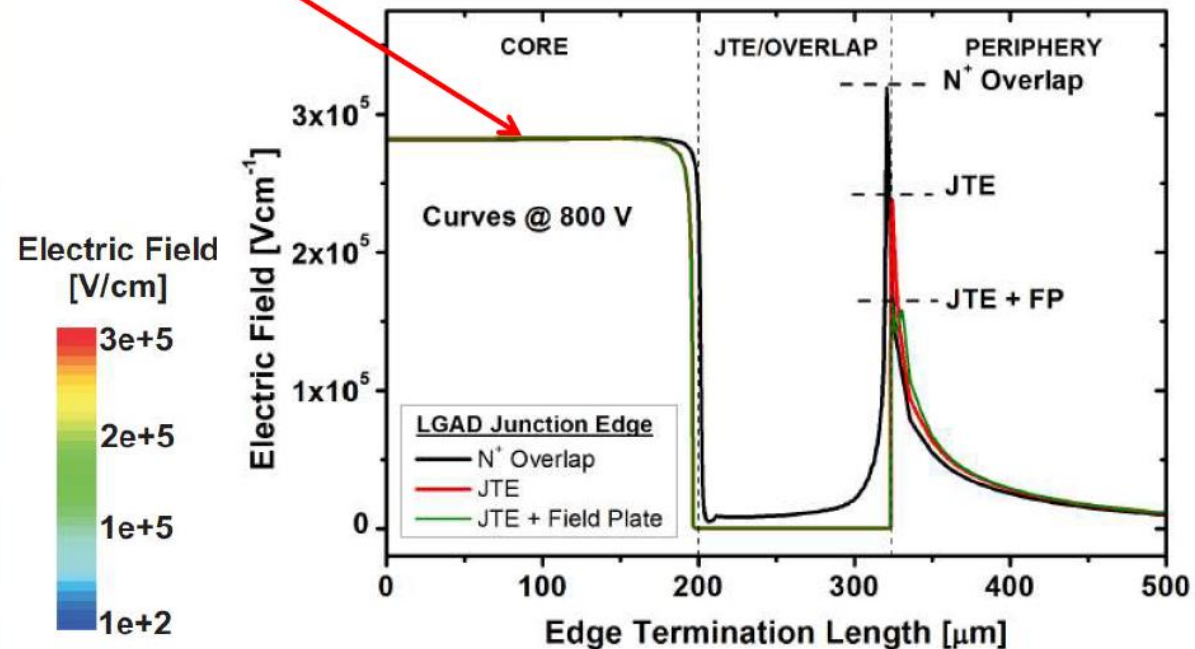
Highest electric field at the plane junction

Gain control

$$V_{BD-Plane} < V_{BD-JTE}$$



Multiplication and avalanche control

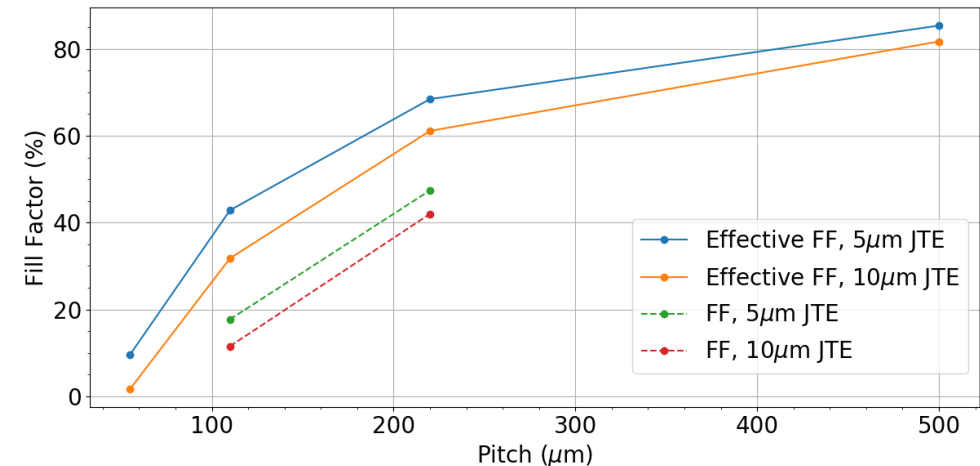
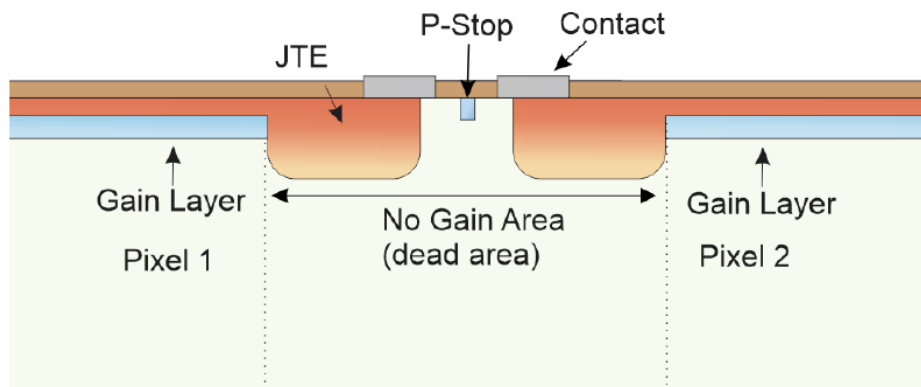


Geometric fill factor

$$\text{Fill Factor} = \frac{\text{Gain Area}}{\text{Total Area}}$$

Caused by JTE around each pixel

Need to take into account diffusion on JTE



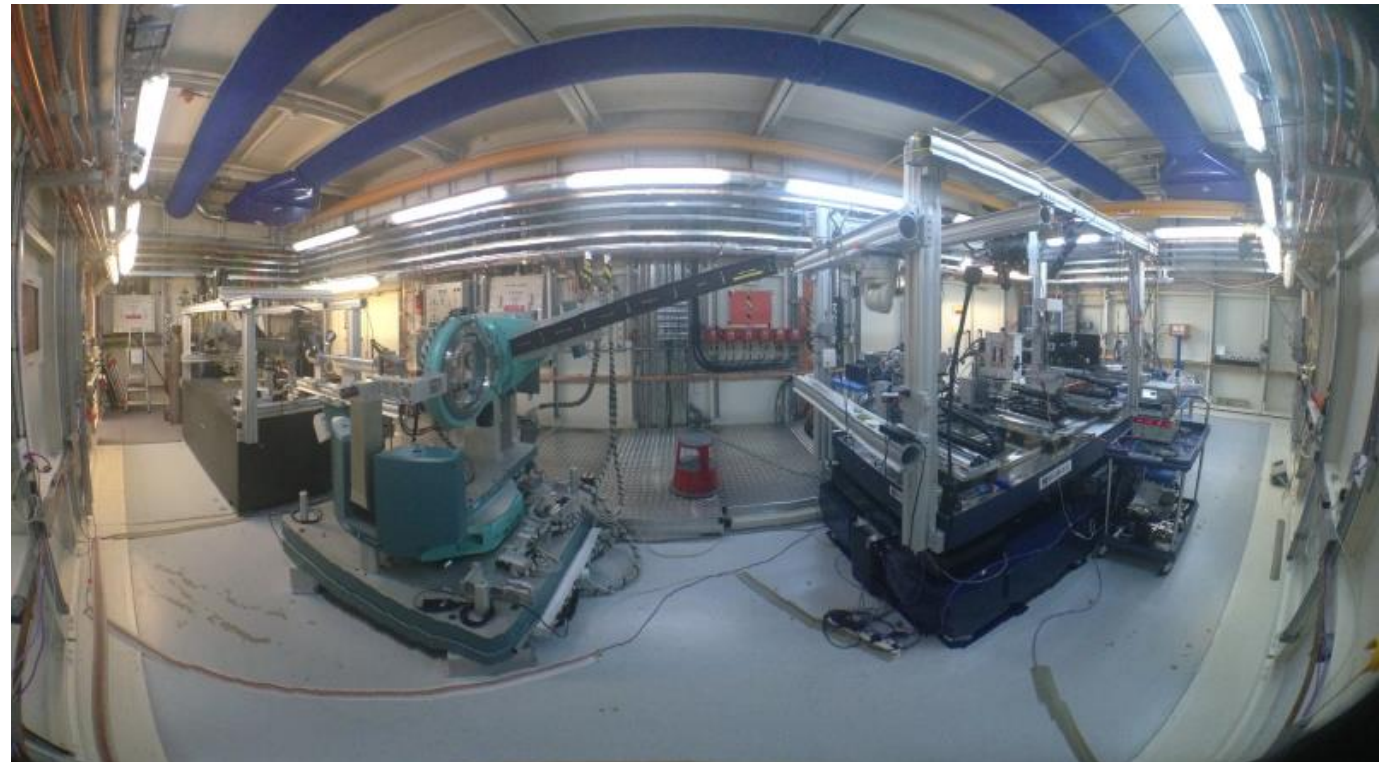
50 x 50 μm² pixel – JTE 10 μm -> fill factor < 10%

B16: Test Beamline

- Flexible and versatile beamline for testing new developments in optics and detector technology and for trialling new experimental techniques
- 4 – 45 keV photon energy range
- Operational modes:
 - Focused, unfocused
 - Monochromatic, white beam
 - High flux

What we use

- 15 keV monochromatic beam
- Focused to about a micron FWHM



Devices produced and tested

- C04 - 110 μm pixel, 10 μm JTE
- C06 - 110 μm pixel, 20 μm JTE
- D04 - 55 μm pixel, 5 μm JTE

- Each device has control no-multiplication region of 9x9 pixels in the right bottom corner

- I will show 110 μm , 10 μm JTE in detail
- I will show 110 μm , 20 μm JTE as comparison to 10 μm JTE
- I will show 55 μm , 5 μm JTE

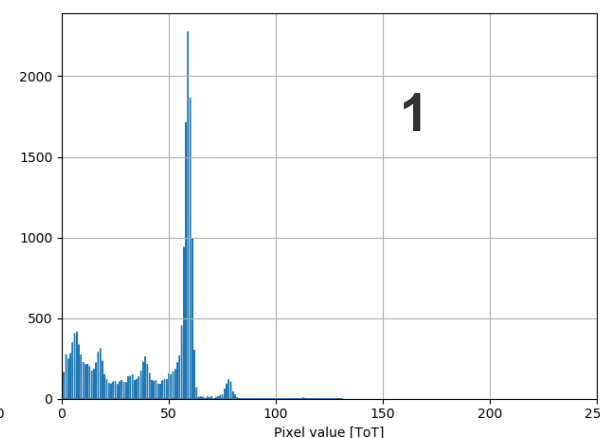
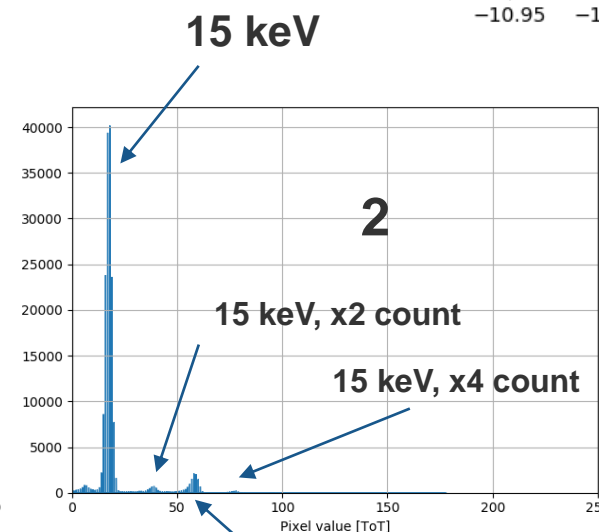
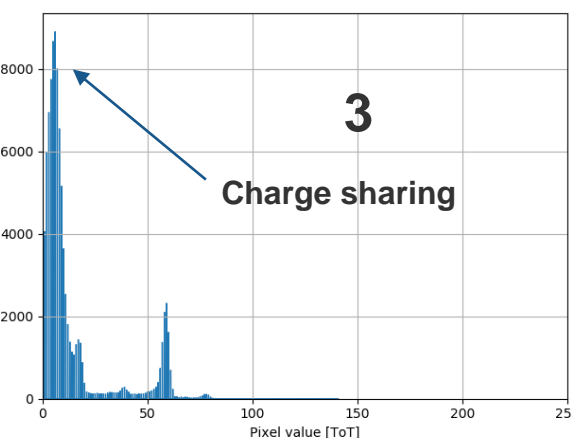
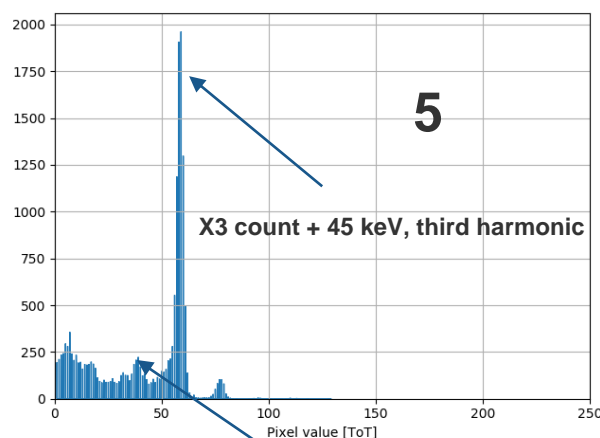
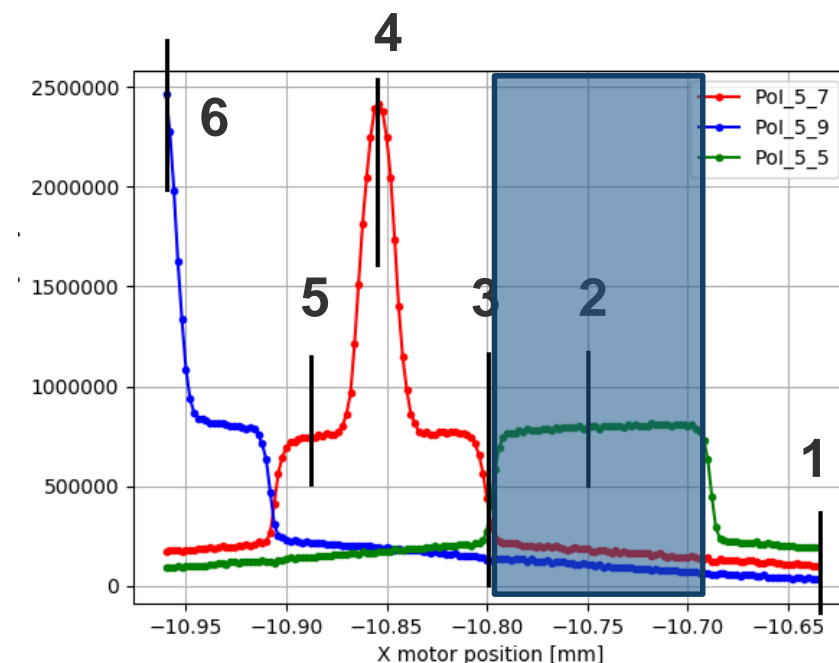
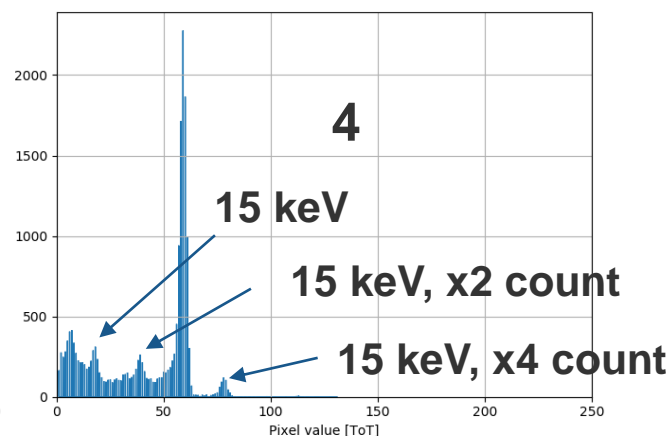
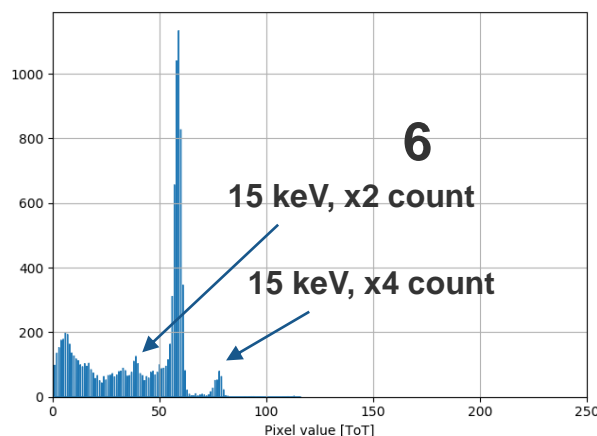
Tests performed

- Line scan over Pixel of Interest (POI) @ V
- Voltage scan in the middle of PoI
- 2D scan @ V_{max}

TPX3 settings

- ToT+ToA mode, data-driven
- AdvaDAQ TPX3 USB3.0

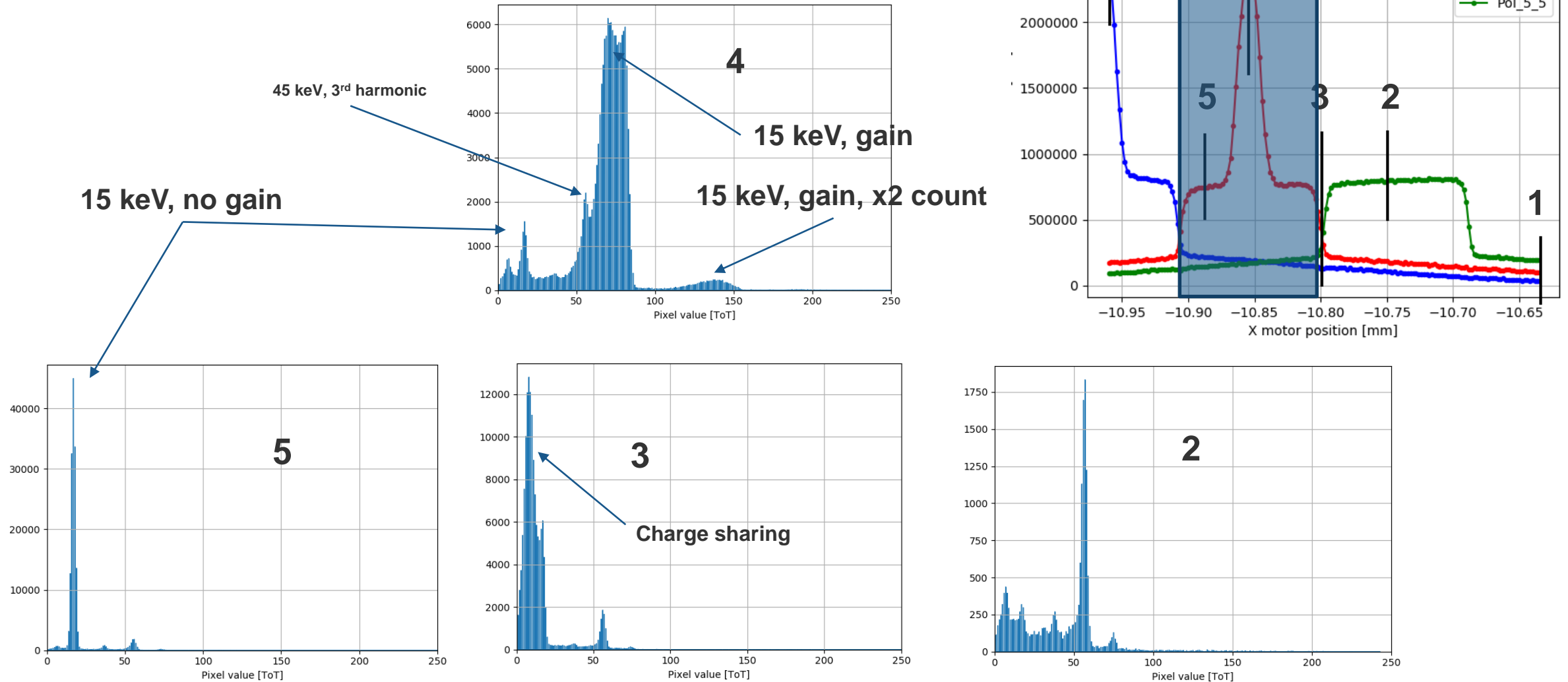
1D line scan, no gain pixel (5, 5), -350V



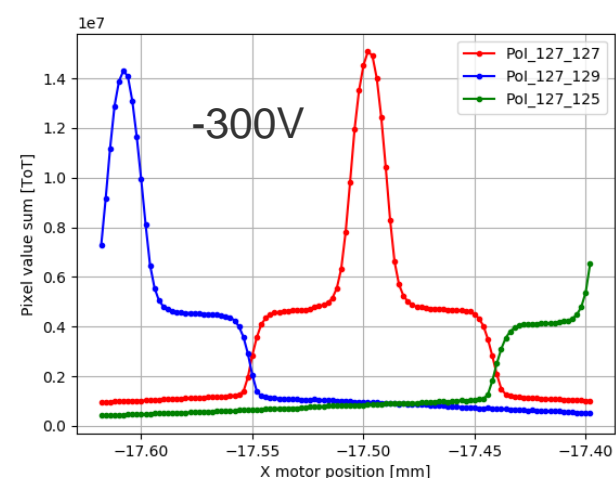
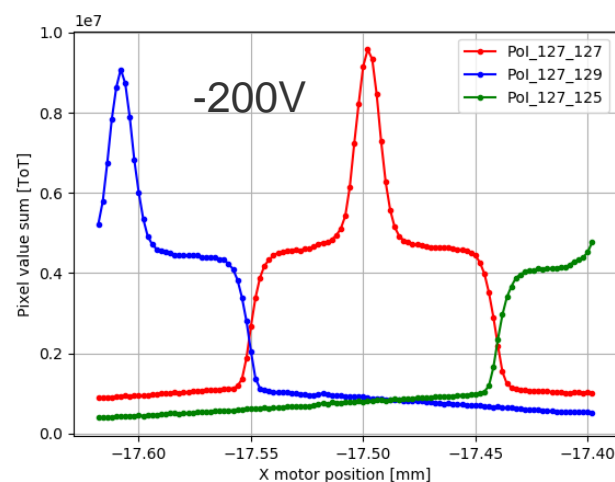
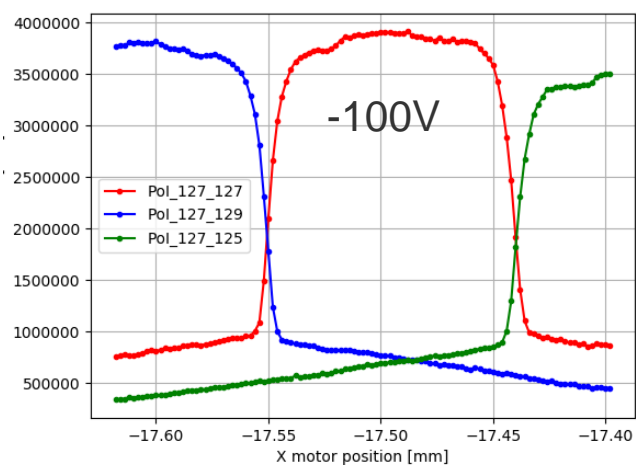
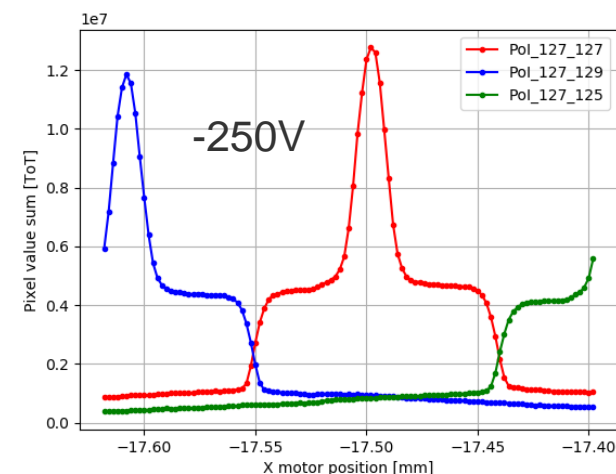
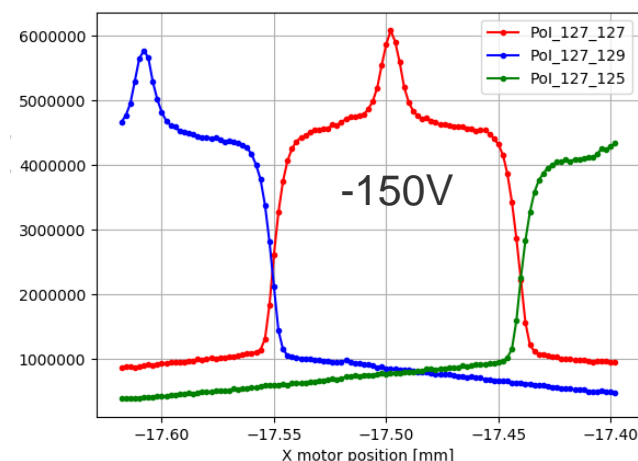
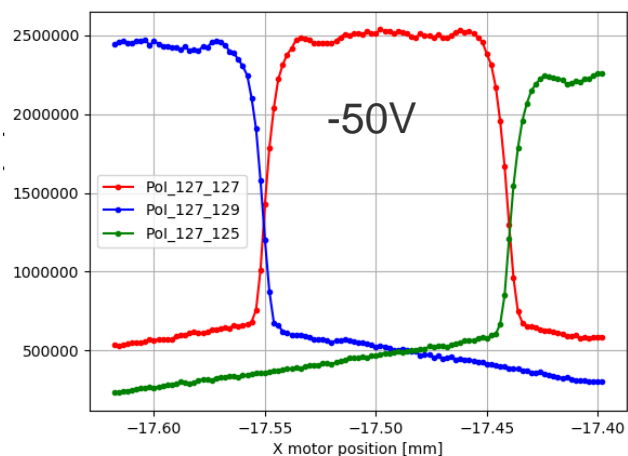
15 keV, x2 count

15 keV, x3 count + 45 keV (3rd harmonic)

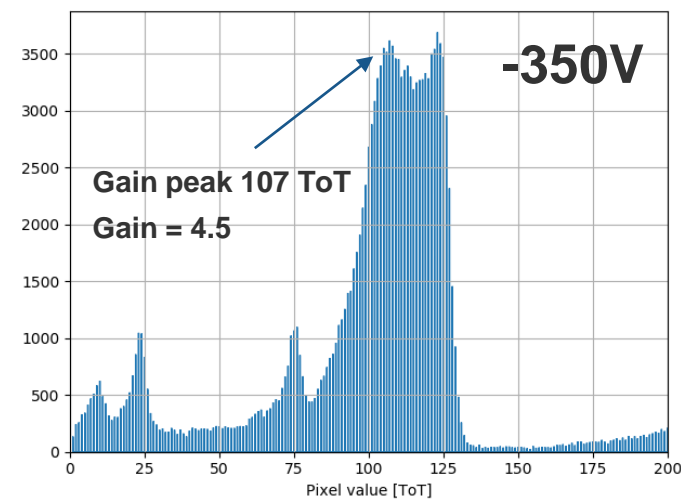
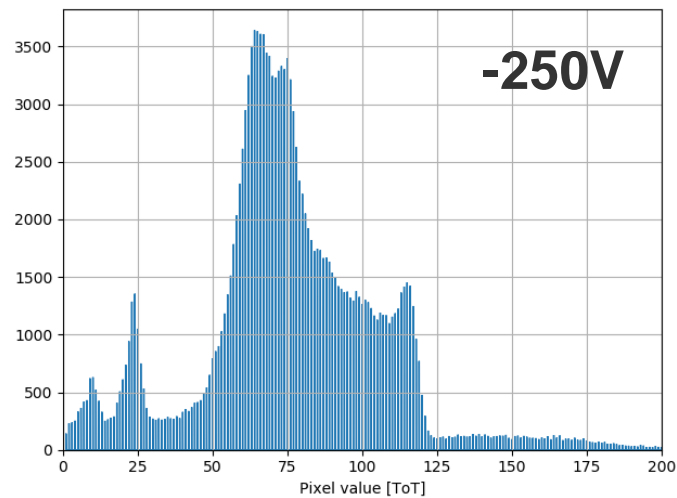
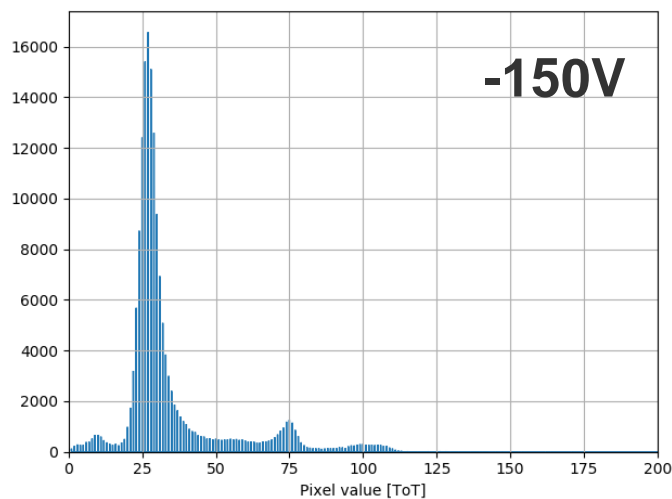
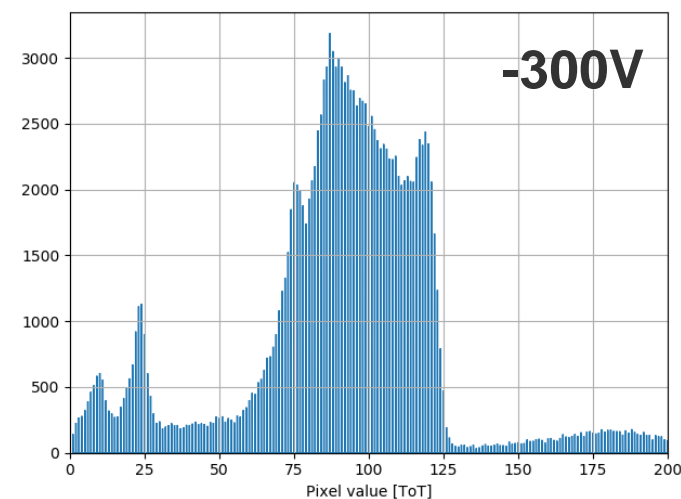
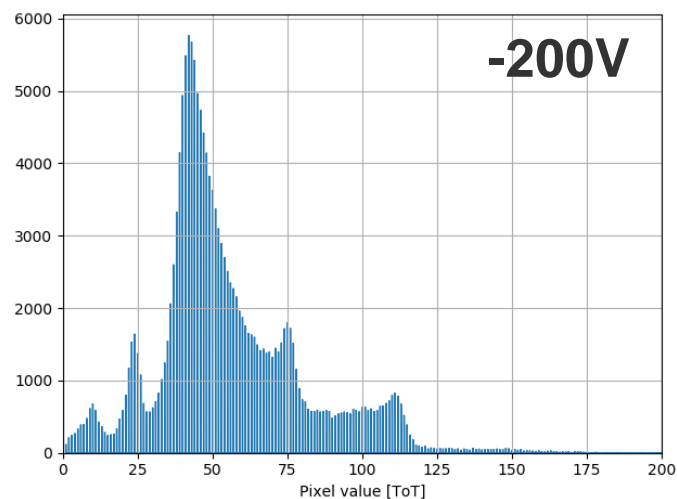
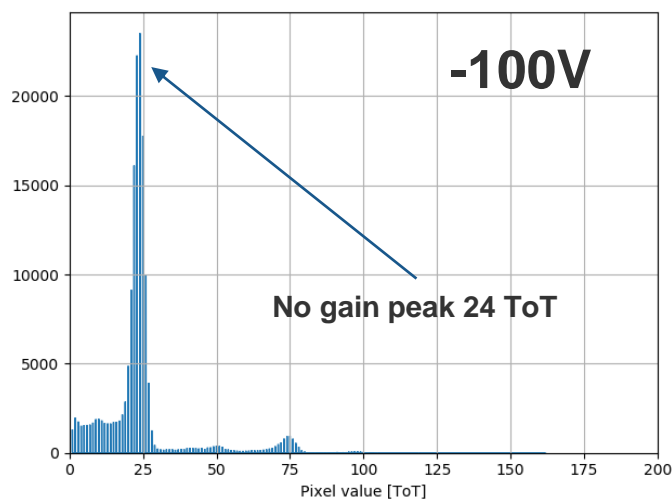
1D line scan, gain pixel (5, 7), -350V



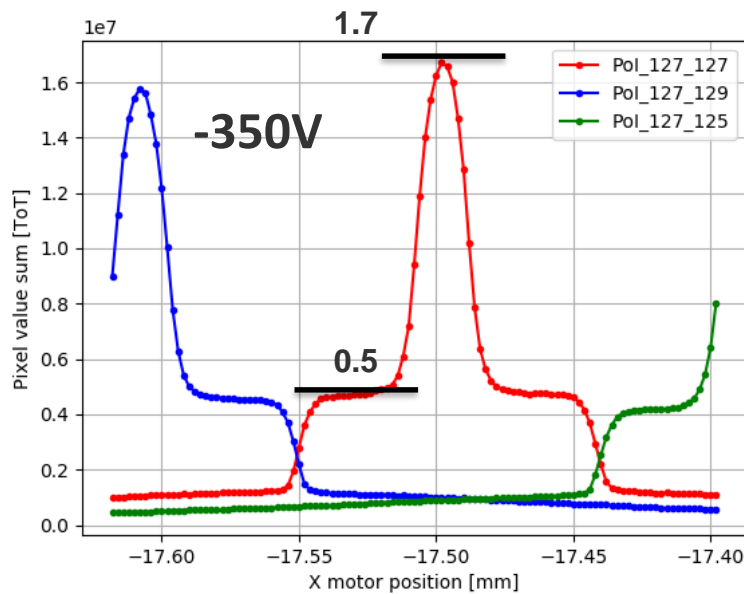
1D line scans @ voltages, gain pixel (127, 127)



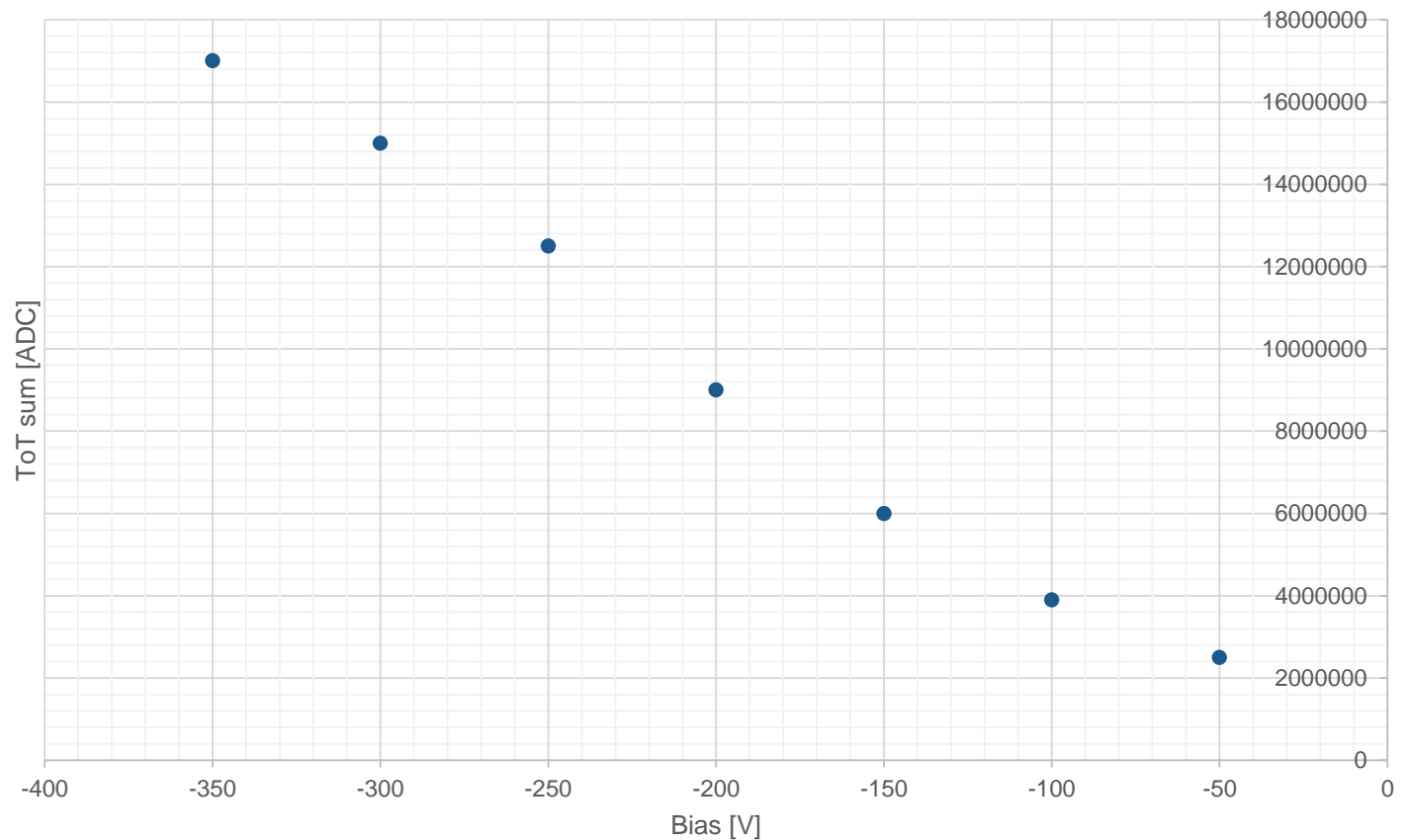
Spectrum in the middle of gain pixel (127, 127)



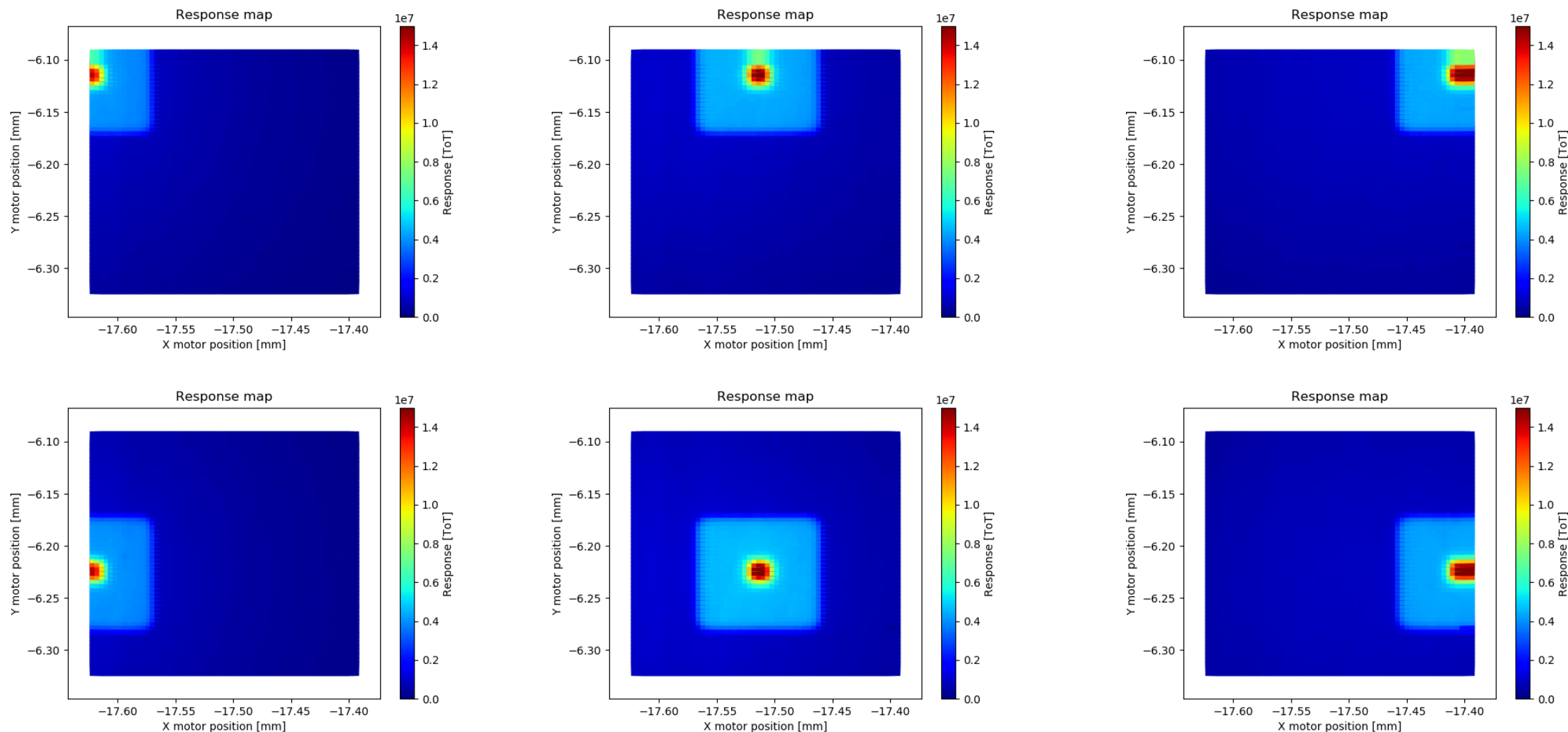
1D line scans @ voltages, gain pixel (127, 127)



Gain: 3.4



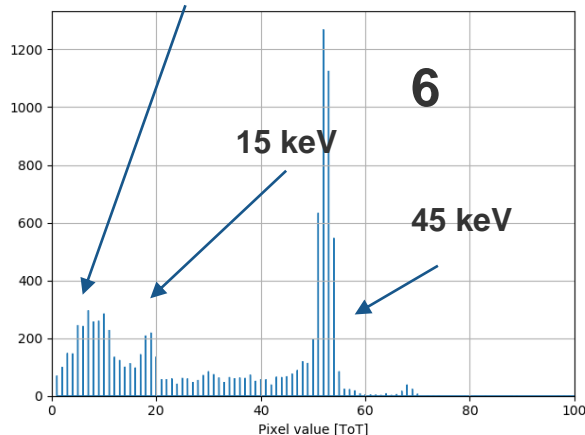
2D scan (-350V)



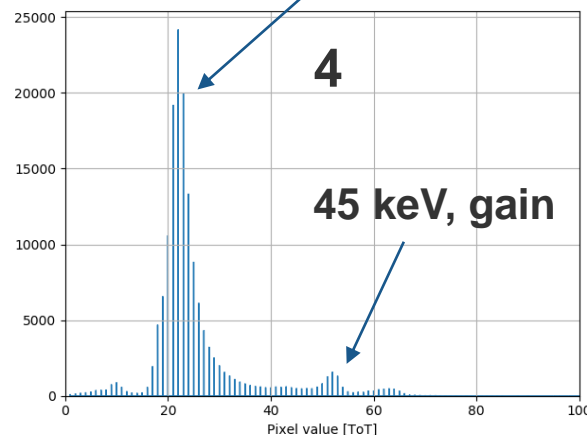
1D line scan, gain pixel (5, 7), -350V

Note! No x2 count peak, so 45 keV is 3rd harmonic only!

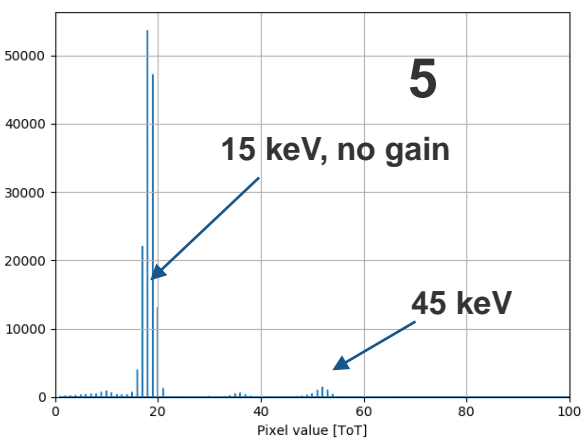
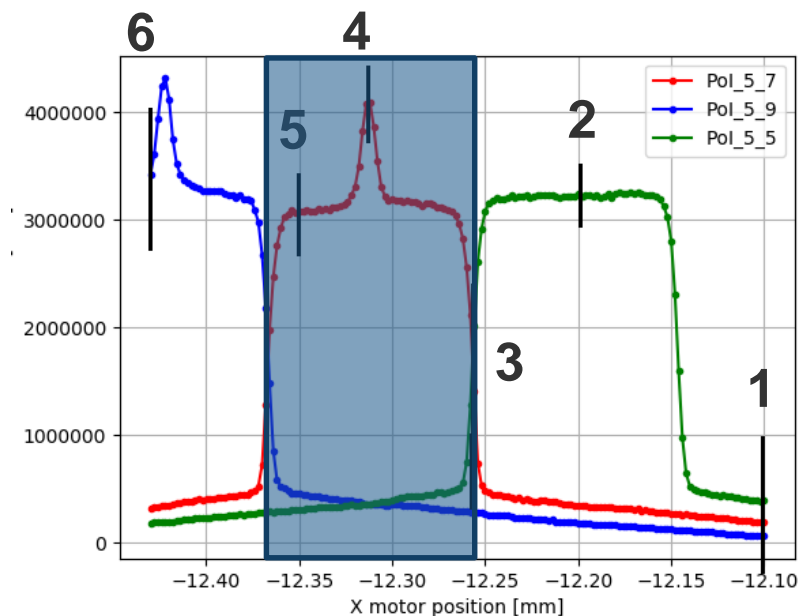
Charge sharing



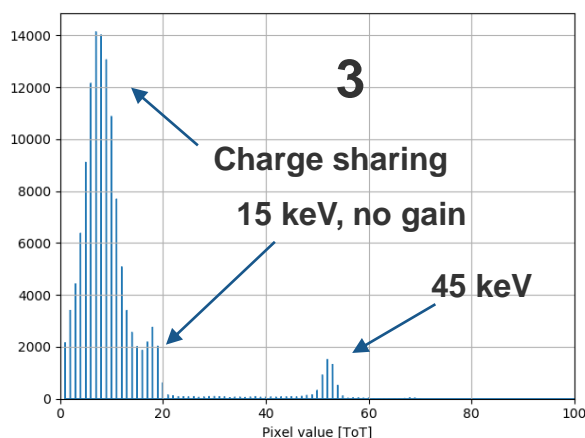
15 keV, gain



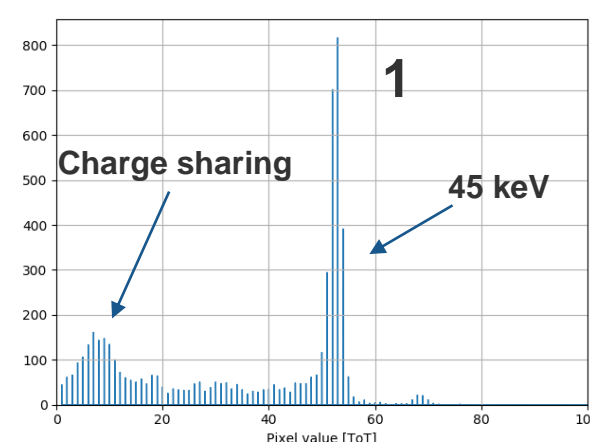
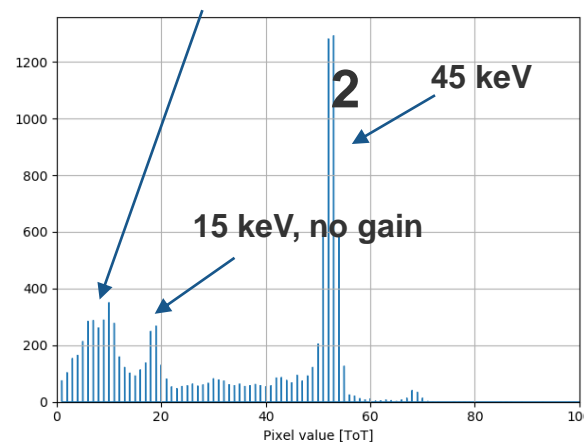
45 keV, gain



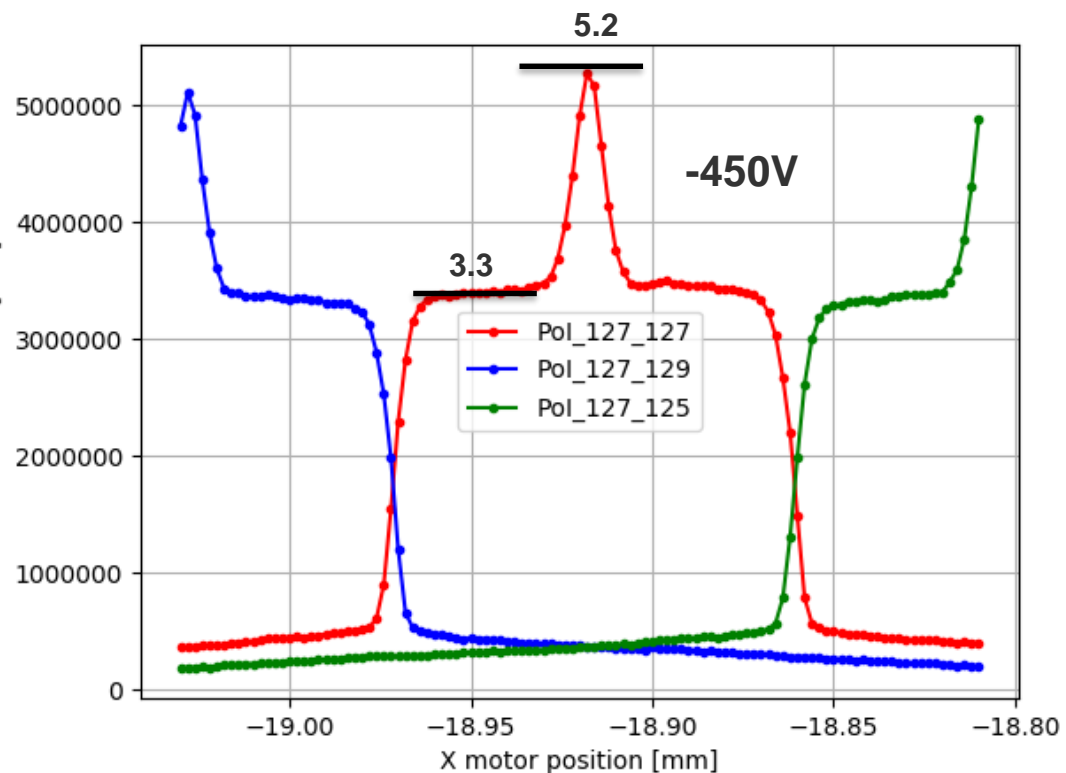
Charge sharing



Charge sharing

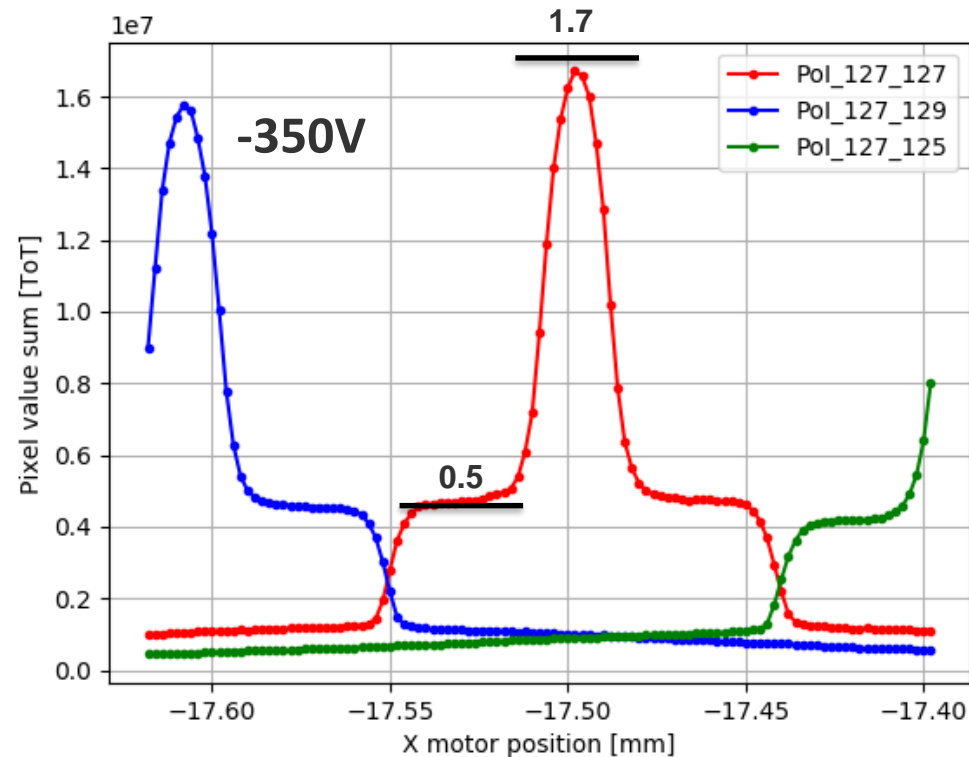


110 um pixel, 20 um JTE



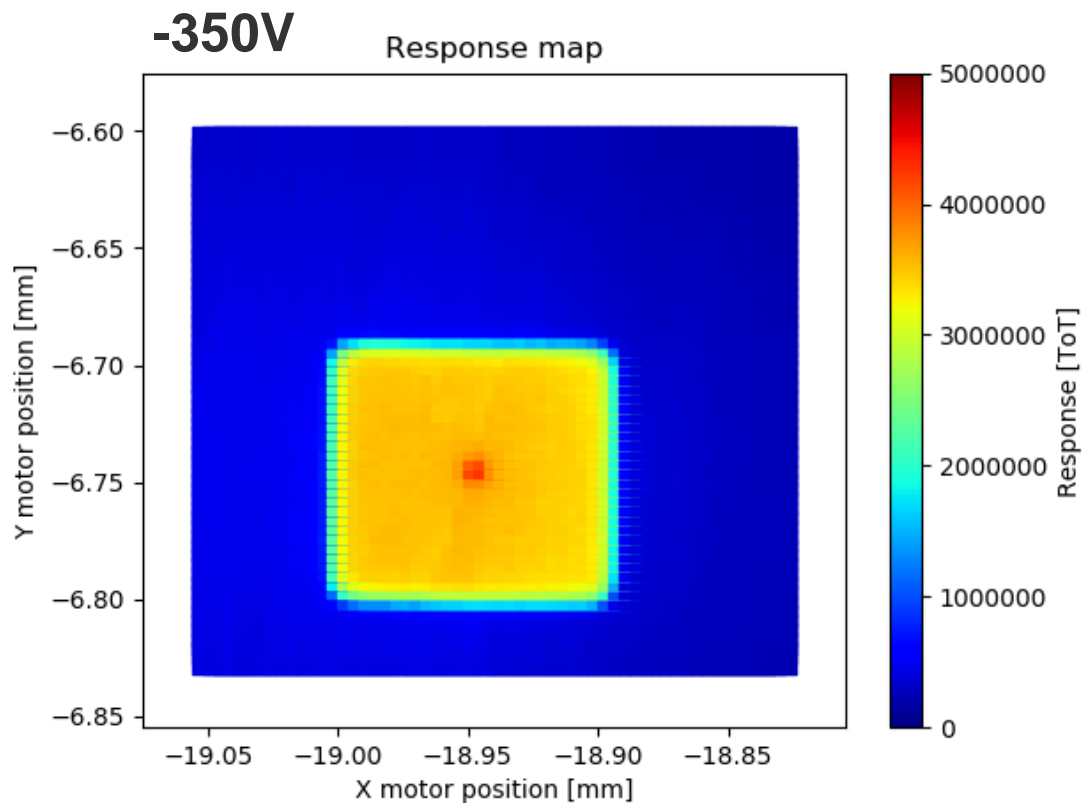
Gain: 1.6

110 um pixel, 10 um JTE

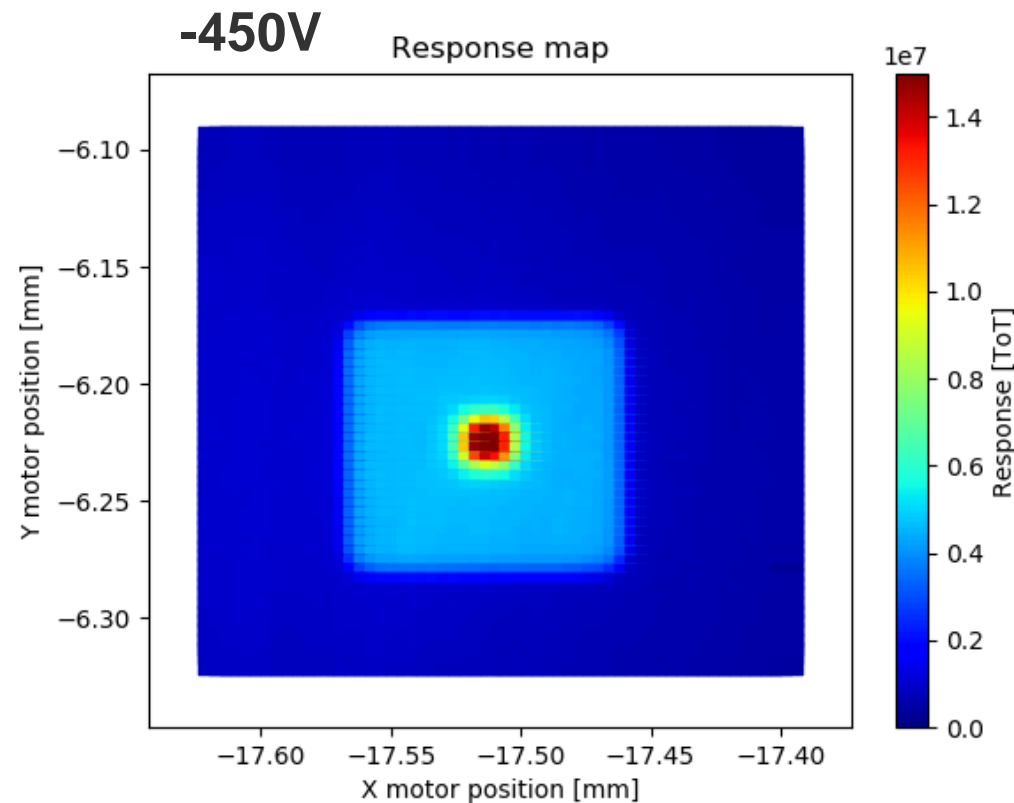


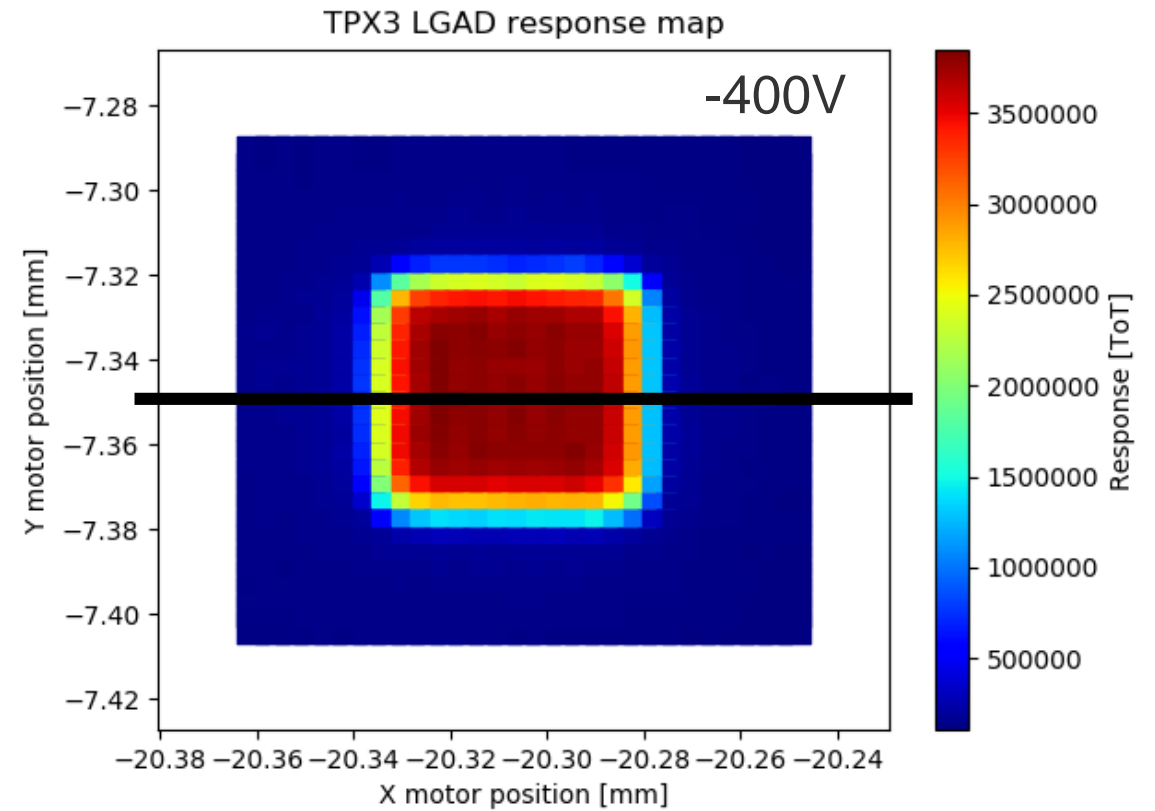
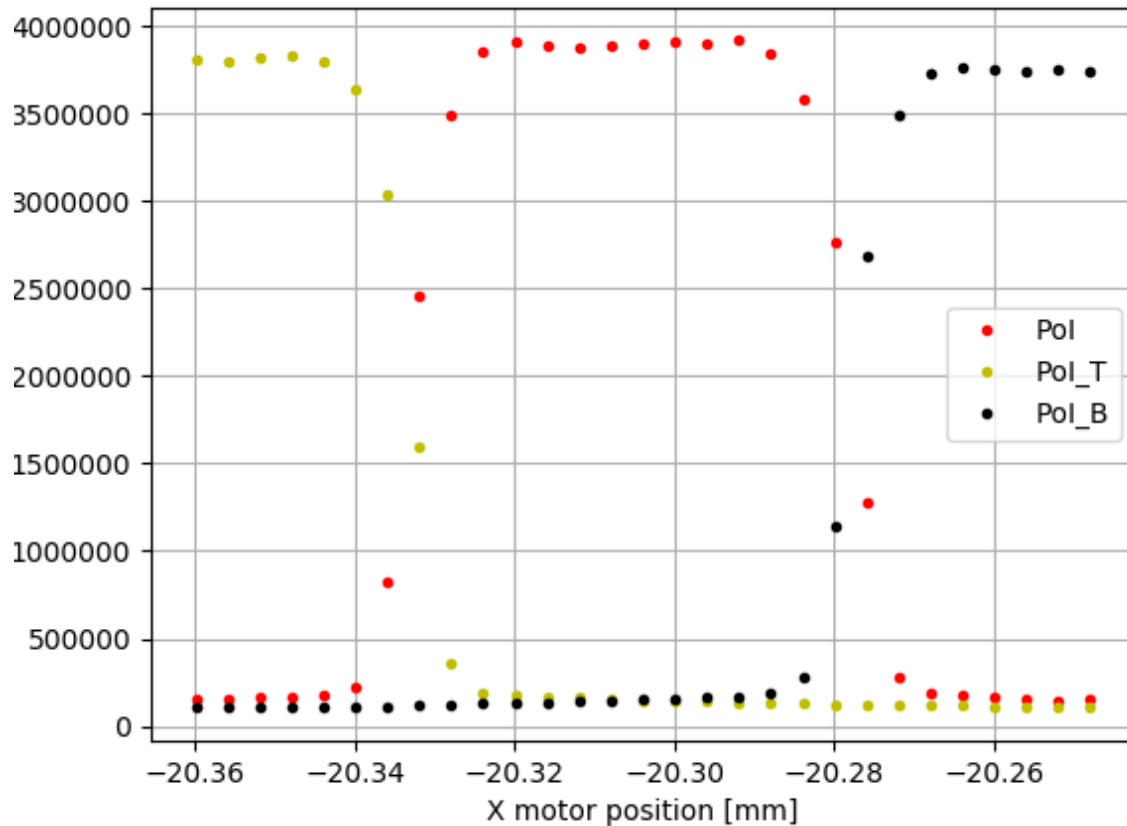
Gain: 3.4

110 um pixel, 20 um JTE



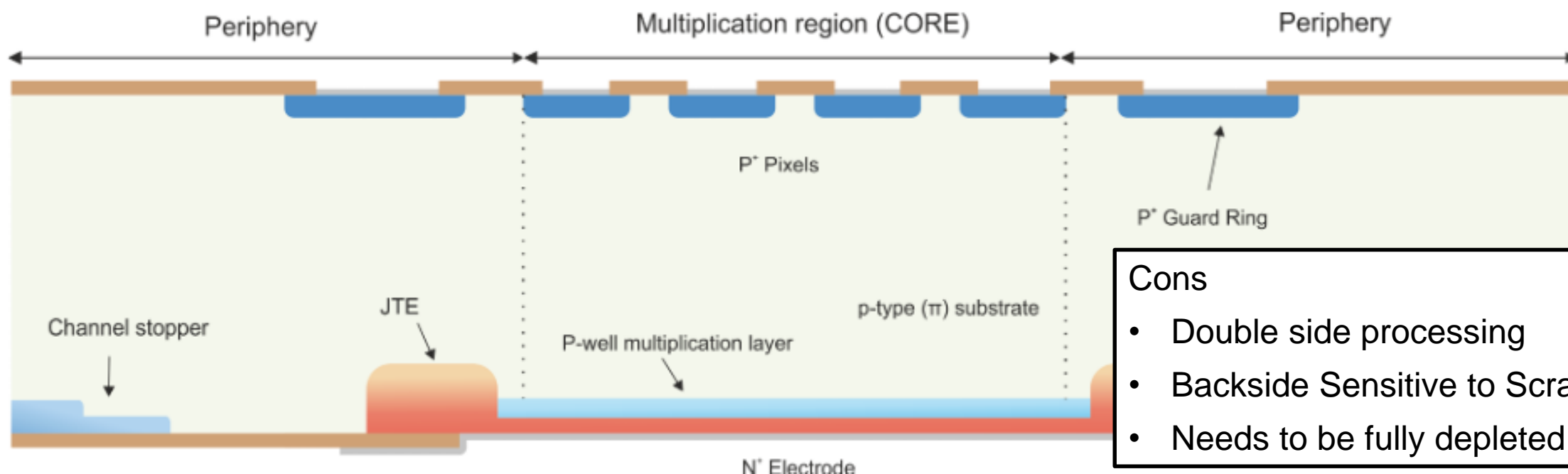
110 um pixel, 10 um JTE





No gain observed as expected

- Segmentation at the **ohmic contact**: strip and pixels.
- **Multiplication** extended over all the **CORE**.
- **P-type collector ring** at the ohmic side to extract leakage current.
- **JTE** to protect the n+/p curvature and **channel stopper** to avoid the depletion reaches the end of the detector.
- Readout is made by the strips/pixels: holes collection.



- Cons**
- Double side processing
 - Backside Sensitive to Scratches
 - Needs to be fully depleted

Summary

- Strong program to design, produce and test LGAD devices
 - TCAD simulations
 - Mask design, device fabrication
 - Device characterisation by means of TCT and X-rays
- Predicted and demonstrated gain in small pixel devices
 - Various pixel sizes
 - Various JTE sizes
- Pathway for overcome existing limitations
 - Inverse LGAD design (fabricated, ready to test)
 - Trench isolation design (work in progress)

